ML144110
ML144111
Digital–to–Analog Converters with Serial Interface

CMOS LSI

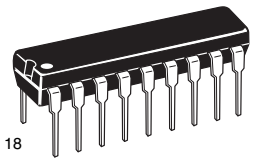
Legacy Device: *Motorola/Freescale MC144110, MC144111*

The ML144110 and ML144111 are low–cost 6–bit D/A converters with serial interface ports to provide communication with CMOS microprocessors and microcomputers. The ML144110 contains six static D/A converters; the ML144111 contains four converters.

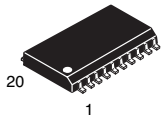
Due to a unique feature of these DACs, the user is permitted easy scaling of the analog outputs of a system. Over a 5 to 15 V supply range, these DACs maybe directly interfaced to CMOS MPUs operating at 5 V.

- Direct R–2R Network Outputs
- Buffered Emitter–Follower Outputs
- Serial Data Input
- Digital Data Output Facilitates Cascading
- Direct Interface to CMOS µP
- Wide Operating Voltage Range: 4.5 to 15 V
- Wide Operating Temperature Range: T_A = 0 to 85°C
- Software Information is Contained in Document M68HC11RM/AD

MC144110

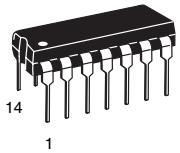


P DIP 18 = VP
PLASTIC DIP
CASE 707

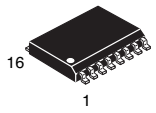


SO 20W = -6P
SOG PACKAGE
CASE 751D

MC144111



P DIP 14 = CP
PLASTIC DIP
CASE 646



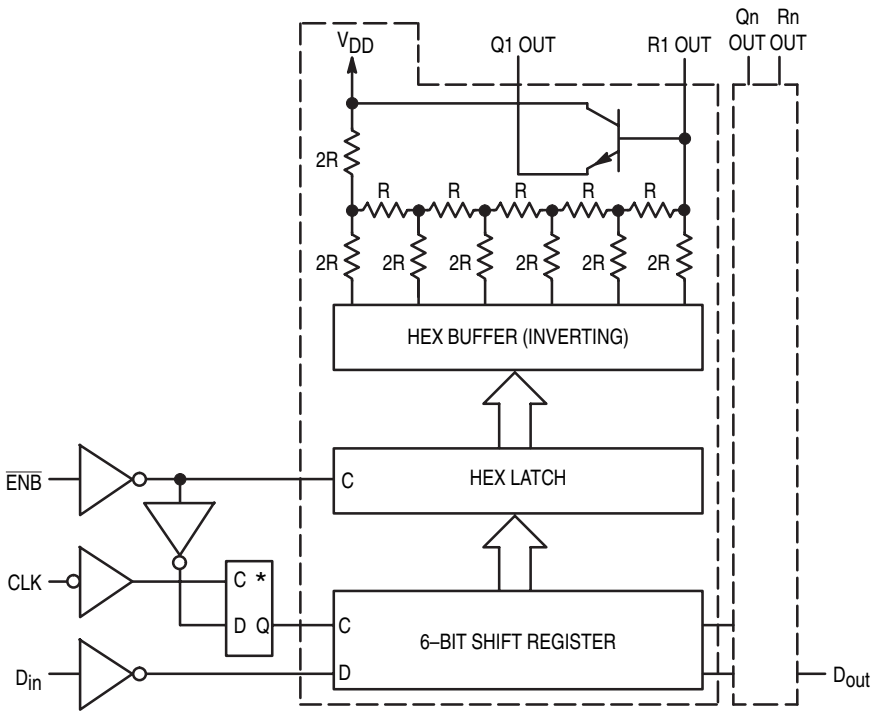
SO 16W = -5P
SOG PACKAGE
CASE 751G

CROSS REFERENCE/ORDERING INFORMATION

PACKAGE	MOTOROLA	LANSDALE
P DIP 18	MC144110P	ML144110VP
SO 20W	MC144110DW	ML144110-6P
P DIP 14	MC144111P	ML144111CP
SO 16W	MC144111DW	ML144111-5P

Note: Lansdale lead free (**Pb**) product, as it becomes available, will be identified by a part number prefix change from **ML** to **MLE**.

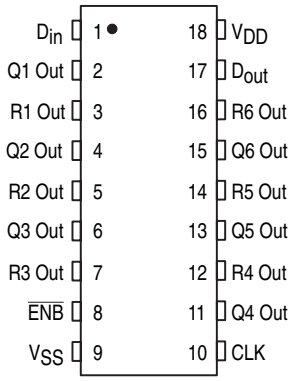
BLOCK DIAGRAM



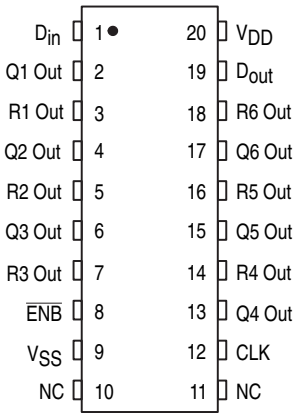
* Transparent Latch

PIN ASSIGNMENTS

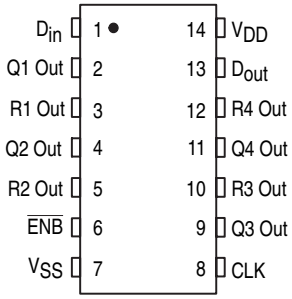
ML144110VP



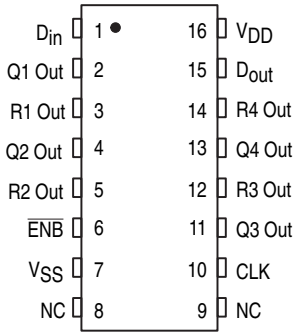
ML144110-6P



ML144111CP



ML144111-5P



NC = NO CONNECTION

MAXIMUM RATINGS* (Voltages referenced to V_{SS})

Parameter	Symbol	Value	Unit
DC Supply Voltage	V_{DD}	– 0.5 to + 18	V
Input Voltage, All Inputs	V_{in}	– 0.5 to V_{DD} + 0.5	V
DC Input Current, per Pin	I	± 10	mA
Power Dissipation (Per Output) T_A = 70°C, MC144110 MC144111 T_A = 85°C, MC144110 MC144111	P_{OH}	 30 50 10 20	mW
Power Dissipation (Per Package) T_A = 70°C, MC144110 MC144111 T_A = 85°C, MC144110 MC144111	P_D	 100 150 25 50	mW
Storage Temperature Range	T_{stg}	– 65 to + 150	°C

* Maximum Ratings are those values beyond which damage to the device may occur.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields; however, it is advised that precautions be taken to avoid application of voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation it is recommended that V_{in} and V_{out} be constrained to the range $V_{SS} \leq (V_{in}$ or $V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}).

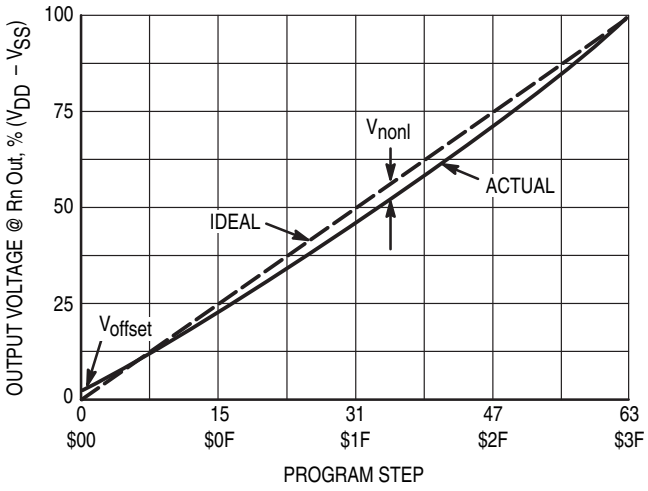
ELECTRICAL CHARACTERISTICS (Voltages referenced to V_{SS}, T_A = 0 to 85°C unless otherwise indicated)

Symbol	Parameter	Test Conditions	V_{DD}	Min	Max	Unit
V_{IH}	High–Level Input Voltage (D_{in}, $\overline{ENB}$, CLK)		5 10 15	3.0 3.5 4	— — —	V
V_{IL}	Low–Level Input Voltage (D_{in}, $\overline{ENB}$, CLK)		5 10 15	— — —	0.8 0.8 0.8	V
I_{OH}	High–Level Output Current (D_{out})	$V_{out} = V_{DD} - 0.5$ V	5	– 200	—	µA
I_{OL}	Low–Level Output Current (D_{out})	V_{out} = 0.5 V	5	200	—	µA
I_{DD}	Quiescent Supply Current ML144110 ML144111	I_{out} = 0 µA	15 15	— —	12 8	mA
I_{in}	Input Leakage Current (D_{in}, $\overline{ENB}$, CLK)	$V_{in} = V_{DD}$ or 0 V	15	—	± 1	µA
V_{nonl}	Nonlinearity Voltage (Rn Out)	See Figure 1	5 10 15	— — —	100 200 300	mV
V_{step}	Step Size (Rn Out)	See Figure 2	5 10 15	19 39 58	137 274 411	mV
V_{offset}	Offset Voltage from V_{SS}	D_{in} = $00, See Figure 1	—	—	1	LSB
I_E	Emitter Leakage Current	$V_{Rn\ Out}$ = 0 V	15	—	10	µA
h_{FE}	DC Current Gain	I_E = 0.1 to 10.0 mA T_A = 25°C	—	40	—	—
V_{BE}	Base–to–Emitter Voltage Drop	I_E = 1.0 mA	—	0.4	0.7	V

SWITCHING CHARACTERISTICS

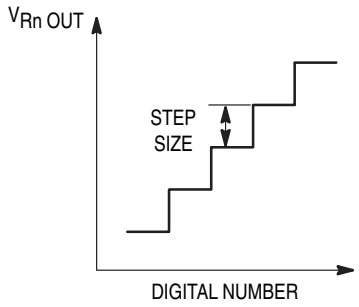
(Voltages referenced to V_{SS}, T_A = 0 to 85°C, C_L = 50 pF, Input $t_r = t_f$ = 20 ns unless otherwise indicated)

Symbol	Parameter	V_{DD}	Min	Max	Unit
t_{wH}	Positive Pule Width, CLK (Figures 3 and 4)	5 10 15	2 1.5 1	— — —	µs
t_{wL}	Negative Pulse Width, CLK (Figure 3 and 4)	5 10 15	5 3.5 2	— — —	µs
t_{su}	Setup Time, $\overline{ENB}$ to CLK (Figures 3 and 4)	5 10 15	5 3.5 2	— — —	µs
t_{su}	Setup Time, D_{in} to CLK (Figures 3 and 4)	5 10 15	1000 750 500	— — —	ns
t_h	Hold Time, CLK to $\overline{ENB}$ (Figures 3 and 4)	5 10 15	5 3.5 2	— — —	µs
t_h	Hold Time, CLK to D_{in} (Figures 3 and 4)	5 10 15	5 3.5 2	— — —	µs
t_r, t_f	Input Rise and Fall Times	5 – 15	—	2	µs
C_{in}	Input Capacitance	5 – 15	—	7.5	pF



LINEARITY ERROR (integral linearity). A measure of how straight a device's transfer function is, it indicates the worst–case deviation of linearity of the actual transfer function from the best–fit straight line. It is normally specified in parts of an LSB.

Figure 1. D/A Transfer Function



$$\text{Step Size} = \frac{V_{DD}}{64} \pm 0.75 \frac{V_{DD}}{64}$$

(For any adjacent pair of digital numbers)

Figure 2. Definition of Step Size

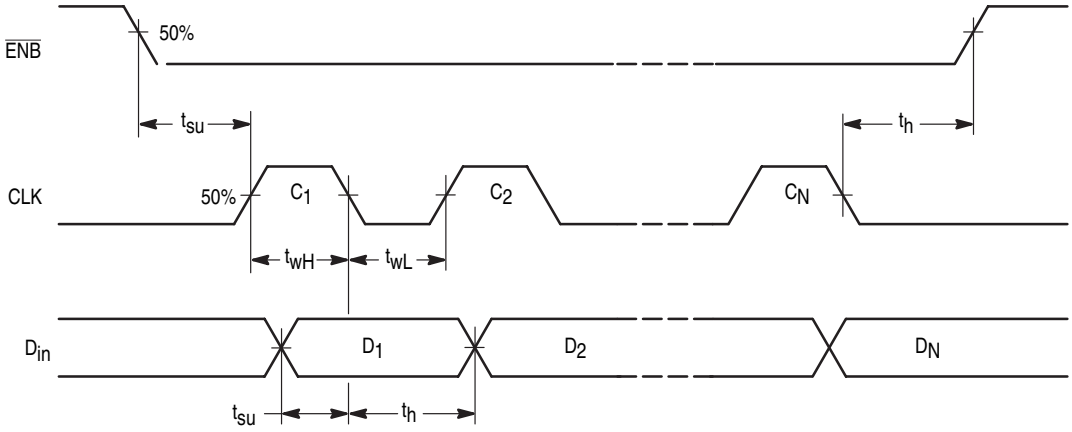


Figure 3. Serial Input, Positive Clock

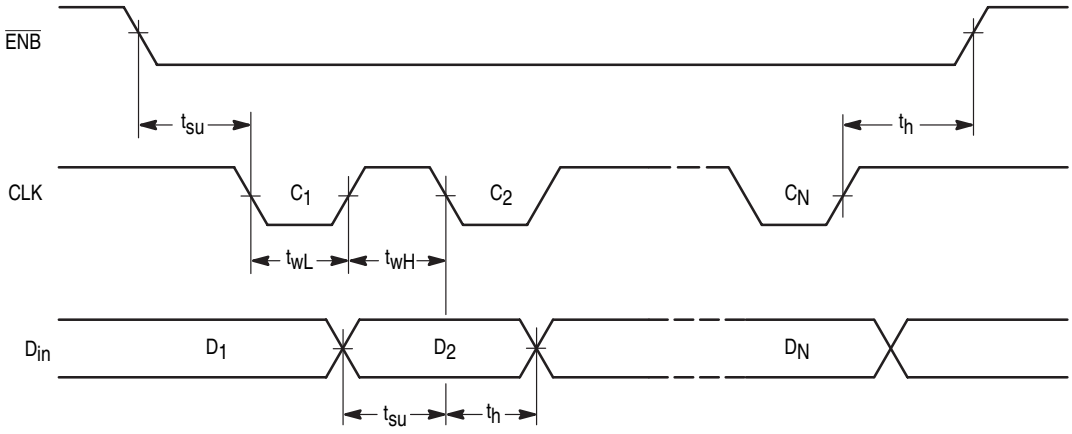


Figure 4. Serial Input, Negative Clock

PIN DESCRIPTIONS

INPUTS

D_{in}
Data Input

Six–bit words are entered serially, MSB first, into digital data input, D_{in}. Six words are loaded into the ML144110 during each D/A cycle; four words are loaded into the ML144111.

The last 6–bit word shifted in determines the output level of pins Q1 Out and R1 Out. The next–to–last 6–bit word affects pins Q2 Out and R2 Out, etc.

$\overline{ENB}$
Negative Logic Enable

The $\overline{ENB}$ pin must be low (active) during the serial load. On the low–to–high transition of $\overline{ENB}$, data contained in the shift register is loaded into the latch.

CLK
Shift Register Clock

Data is shifted into the register on the high–to–low transition of CLK. CLK is fed into the D–input of a transparent latch, which is used for inhibiting the clocking of the shift register when $\overline{ENB}$ is high.

The number of clock cycles required for the ML144110 is usually 36. The ML144111 usually uses 24 cycles. SeeTable 1 for additional information.

OUTPUTS

D_{out}
Data Output

The digital data output is primarily used for cascading the DACs and may be fed into D_{in} of the next stage.

R1 Out through Rn Out
Resistor Network Outputs

These are the R–2R resistor network outputs. These outputs may be fed to high–impedance input FET op amps to bypass the on–chip bipolar transistors. The R value of the resistor network ranges from 7 to 15 kΩ.

Q1 Out through Qn Out
NPN Transistor Outputs

Buffered DAC outputs utilize an emitter–follower configuration for current–gain, thereby allowing interface to low–impedance circuits.

SUPPLY PINS

V_{SS}
Negative Supply Voltage

This pin is usually ground.

V_{DD}
Positive Supply Voltage

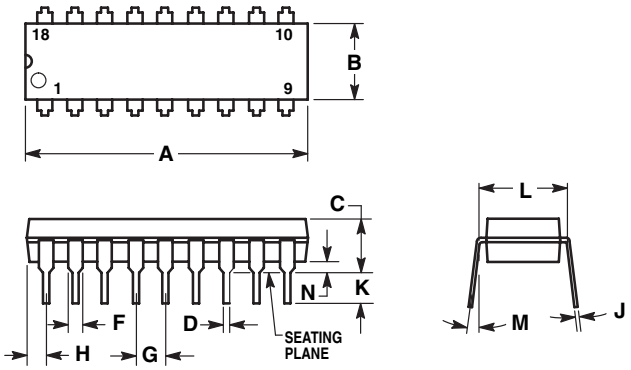
The voltage applied to this pin is used to scale the analog output swing from 4.5 to 15 V p–p.

Table 1. Number of Channels vs Clocks Required

Number of Channels Required	Number of Clock Cycles	Outputs Used on ML144110	Outputs Used on ML144111
1	6	Q1/R1	Q1/R1
2	12	Q1/R1, Q2/R2	Q1/R1, Q2/R2
3	18	Q1/R1, Q2/R2, Q3/R3	Q1/R1, Q2/R2, Q3/R3
4	24	Q1/R1, Q2/R2, Q3/R3, Q4/R4	Q1/R1, Q2/R2, Q3/R3, Q4/R4
5	30	Q1/R1, Q2/R2, Q3/R3, Q4/R4, Q5/R5	Not Applicable
6	36	Q1/R1, Q2/R2, Q3/R3, Q4/R4, Q5/R5, Q6/R6	Not Applicable

OUTLINE DIMENSIONS

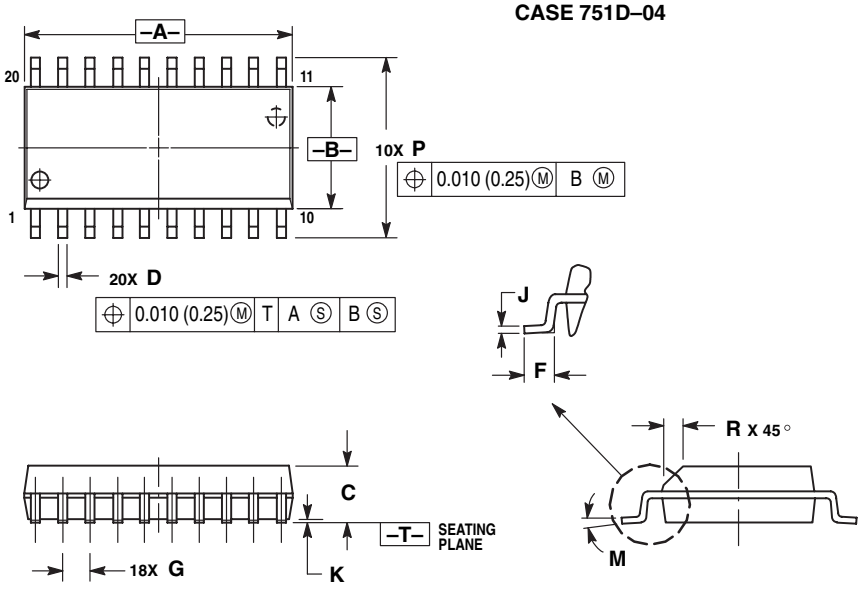
P DIP 18 = VP
(ML144110VP)
PLASTIC DIP
CASE 707–02



NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	22.22	23.24	0.875	0.915
B	6.10	6.60	0.240	0.260
C	3.56	4.57	0.140	0.180
D	0.36	0.56	0.014	0.022
F	1.27	1.78	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	1.02	1.52	0.040	0.060
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

SO 20W = -6P
(ML144110-6P)
SOG PACKAGE
CASE 751D–04

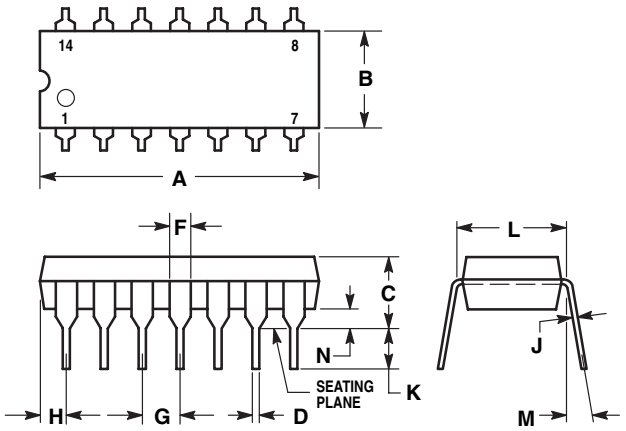


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

OUTLINE DIMENSIONS

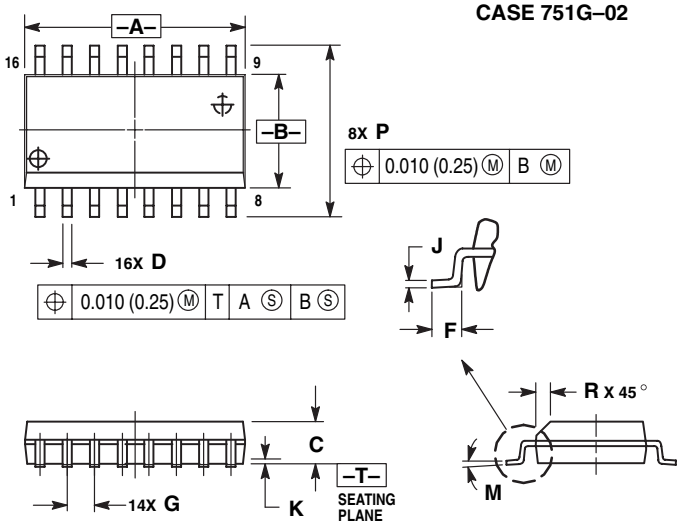
P DIP 14 = CP
(ML144111CP)
PLASTIC DIP
CASE 646–06



NOTES:
1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
4. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.300 BSC		7.62 BSC	
M	0°	10°	0°	10°
N	0.015	0.039	0.39	1.01

SO 16W = -5P
(ML144111-5P)
SOG PACKAGE
CASE 751G–02



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029